

SLOVENSKI STANDARD oSIST prEN IEC 61249-2-52:2024

01-december-2024

Materiali za plošče tiskanih vezij in druge povezovalne strukture - 2-52. del: Pokovinjeni in nepokovinjeni ojačeni osnovni materiali - Duromeri na osnovi ogljikovodikov, laminati, ojačeni s tkanino iz e-stekla z definirano gorljivostjo (preskus navpične gorljivosti), bakrena obloga

Materials for printed boards and other interconnecting structures - Part 2-52: Reinforced base materials clad and unclad - Thermosetting hydrocarbon resin system, woven eglass reinforced laminate sheets of defined flammability (vertical burning test), copperclad

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ICS:

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards

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91/1977/CDV

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Japan		Mr Osamu IKEDA		
OF INTEREST TO THE FOLLOWING COMMITTEES:		HORIZONTAL FUNCTION(S):		
ASPECTS CONCERNED:	:Tob Cto	ndordo		
SUBMITTED FOR CENELEC PARALLE		☐ NOT SUBMITTED FOR CENELEC PARALLEL VOTING		
Attention IEC-CENELEC parallel vo	ting//stand	lards.it		
The attention of IEC National Committees, members of CENELEC, is drawn to the fact that this Committee Draft for Vote (CDV) is submitted for parallel voting.				
The CENELEC members are invited to vote through the CENELEC online voting system. OSIST PREMIED 61249-2-52:2024 ards.iteh.ai/catalog/standards/sist/517f88d8-e5cb-4a9d-85af-042746bf6d32/osist-pren-iec-61249				
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TITLE:				
Materials for printed boards and other interconnecting structures - Part 2-52: Reinforced base materials clad and unclad - Thermosetting hydrocarbon resin system, woven E-glass reinforced laminate sheets of defined flammability (vertical burning test), copper-clad				
PROPOSED STABILITY DATE: 2031				
Note from TC/SC officers:				

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 2-52: Reinforced base materials clad and unclad-Thermosetting hydrocarbon resin system, woven E-glass reinforced laminate sheets of defined flammability (vertical burning test), copper-clad

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- International Standard IEC 61249-2-52 has been prepared by subcommittee XX: TITLE, of IEC technical committee TC:91.
- 143 The text of this International Standard is based on the following documents:

FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

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- Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.
- 147 This document has been drafted in accordance with the ISO/IEC Directives, Part 2.
- The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to
- the specific document. At this date, the document will be
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- 154 amended.

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The National Committees are requested to note that for this document the stability date is 2031..

158 THIS TEXT IS INCLUDED FOR THE INFORMATION OF THE NATIONAL COMMITTEES AND WILL BE DELETED AT THE PUBLICATION STAGE.

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Part 2-52: Reinforced base materials clad and unclad-Thermosetting hydrocarbon resin system, woven E-glass reinforced laminate sheets of defined flammability (vertical burning test), copper-clad

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Scope 171

- This part of IEC 61249 gives requirements for properties of Thermosetting hydrocarbon resin 172
- system, woven E-glass reinforced laminate sheets of defined flammability (vertical burning 173
- test), copper-clad in thicknesses of 0,05 mm up to 3,20 mm. 174

Normative references

- The following documents are referred to in the text in such a way that some or all of their 176
- content constitutes requirements of this document. For dated references, only the edition cited 177
- applies. For undated references, the latest edition of the referenced document (including any 178
- amendments) applies. 179
- IEC 61189-2:2006, Test methods for electrical materials, printed boards and other 180
- interconnection structures and assemblies Part 2: Test methods for materials and other 181
- interconnection structures 182
- 183 IEC 61249-5-1, Materials for interconnection structures – Part 5: Sectional specification set
- for conductive foils and films with or without coatings Section 1: Copper foils (for the 184
- manufacture of copper-clad base materials) 185
- IEC/PAS 61249-6-3, Specification for finished fabric woven from E-glass for printed boards
- ISO 11014:2009, Safety data sheet for chemical products Content and order of sections 187

Terms and definitions

- No terms and definitions are listed in this document. 189
- ISO and IEC maintain terminological databases for use in standardization at the following 190 addresses:
- 191
- IEC Electropedia: available at http://www.electropedia.org/ 192
- ISO Online browsing platform: available at http://www.iso.org/obp 193

Materials and Construction 194

4.1 General 195

The sheet consists of an insulating base with metal-foil bonded to one side or both. 196

4.2 Resin system

- The primary resin is polyolefin resin or its modification, copolymers, derivatives. Filler, 198
- accessory ingredient may be added to improve performance. 199

Metal foil 200

- Copper as specified in IEC 61249-5-1, copper foil (for the manufacture of copper-clad 201
- materials). The preferred foils are electrodeposited of defined ductility. 202

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4.4 Reinforcement

Woven E-glass as specified in IEC/PAS 61249-6-3, woven E-glass fabric (for the manufacture of prepreg and copper clad materials). Low permittivity E-glass maybe used to improve dielectric performance.

5 Internal marking

208 Not specified.

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6 Electrical properties

The requirements for electrical properties are shown in Table 1.

Table 1 - Electrical properties

Property	Test method IEC 61189-2	Requirements
Surface resistance after damp heat while in the humidity chamber (optional)	2E03	≥10 000 M Ω
Surface resistance after damp heat and recovery	2E03	≥50 000 M Ω
Volume resistivity after damp heat while in the humidity chamber (optional)	St2E04lar	≥5 000 M Ω • m
Volume resistivity after damp heat and recovery	an 2E04 ds.	10 000 MΩ • m
Permittivity at 10GHz, as received	IPC-TM650- 2.5.5.5	Type A: ≤2.75 Type B: >2.75,≤6.0 Type C: >6.0
Permittivity at 10GHz, as received	IEC 61189-2- 721	As agreed upon by user and
Dissipation factor at 10GHz, as received	IEC 61189-2- 721	≤0,005
Thermal coefficient of Permittivity absolute value at 10GHz, -40 $^{\circ}$ C $^{\circ}$	IEC 61189-2- 721	≤600 ppm/° C
Electric strength(only for material thicknesses <0,5 mm)	2E02	≥30 kV/mm
Arc resistance (only for material thicknesses ≥ 0,5 mm thickness)	2E14	≥60 s
Dielectric breakdown (only for material thicknesses ≥ 0,5 mm thickness)	2E15	≥40 kV
Surface resistance at 125 °C	2E03	≥1 000 M Ω
Volume resistivity at 125 °C	2E03	≥1 000 M Ω • m
a Dielectric Permittivity Tolerance of	san ha chasan as	the following telerance: a) +

 $[^]a$ Dielectric Permittivity Tolerance can be chosen as the following tolerance: a) \pm 0,02;b) \pm 0,04;c) \pm 0,05;d) \pm 0,25;e) \pm 0,50.To be agreed upon by user and supplier.

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7 Non-electrical properties of the copper-clad laminate

7.1 Appearance of the copper-clad sheet

214 7.1.1 General

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- The copper-clad face shall be substantially free from defects that may have an impact on the material's fitness for use for the intended purpose.
- For the following specific defects the requirements given shall apply when inspection is carried out in accordance with IEC 61189-2, method 2M18.

7.1.2 Indentations (pits and dents)

The size of an indentation, usually the length, shall be determined and given a point value to be used as measure of the quality, see Table 2.

Table 2 – Indentations

Size	Point value for each
mm	indentation
0,13-0,25	1
0,26-0,50	2
0,51-0,75	4
0,76-1,00	7
Over 1,00	30

223 The total point count for any 300 mm × 300 mm area shall be calculated to determine the 224 indentation class of the material.

225 Class A 29 maximum

226 Class B 17 maximum

227 Class C 5 maximum

228 Class D 0

229 nd Class X al/ca To be agreed upon by user and supplier 85af-042746bf6d32/osist-pren-iec-61249-2-52-2024

230 The required indentation class of material shall be specified in the purchase order. Indentation

231 Class A applies unless otherwise specified.

232 7.1.3 Wrinkles

There shall be no wrinkles in the copper surface.

234 **7.1.4 Scratches**

- 235 Scratches deeper than 20 % of the nominal thickness of the foil thickness are not allowed.
- Scratches with a depth less than 5 % of the nominal thickness of the foil shall not be counted.
- Scratches with a depth between 5 % and 20 % of the nominal thickness of the foil are permitted to a total length of 100 mm for a 300 mm \times 300 mm area.

239 7.1.5 Raised areas

- Raised areas are usually impressions caused by defects in the press plates used during manufacture but may also be caused by blisters or inclusions of foreign particles under the foil.
- Raised areas caused by blisters or inclusions are not permitted.
- Raised areas caused by impressions of defects in press plates are permitted to the following
- 244 extent:
- 245 Class A and X material Maximum height 15 μm and maximum length 15 mm